

To the Director, U.S. Patent and Trademark

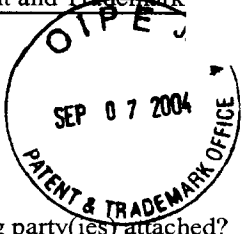


Documents or copy thereof.

1. Name of conveying party(ies):

Makoto HIGASHIKAWA

9/7/04



102833518

Receiving party(ies):

Name: CANON KABUSHIKI KAISHA

Foreign Address: 3-30-2, Shimomaruko, Ohta-ku

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Domestic Address:

City: State ZIP

Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:

- Assignment Merger
- Security Agreement Change of Name
- Other

Execution Date: June 2, 2004

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application Number: 10/834,836
Filing Date: April 30, 2004

B. Title of Invention: METHOD OF FORMING SEMICONDUCTOR DEVICE

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Fitzpatrick, Cella, Harper & Scinto

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Telephone No.: (212) 218-2100

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6. Number of applications and patents involved:

One

7. Total fee (37 CFR 3.41): \$ 40.00

- Enclosed
- Authorized to be charged to deposit account

8. Deposit account number (for deficiency or excess)

06-1205

(Attach duplicate copy of this page if paying by deposit account):

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and the attached is the original document or is a true copy of the original document.

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Damond E. Vadnais, Reg. No. 52,310

Name of Person Signing

Damond Vadnais
Signature

September 7, 2004

Date

Total number of pages including cover sheet, attachments, and documents: 2

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SOLE
(AFTER APPLICATION FILED)

ASSIGNMENT OF PATENT RIGHTS FOR THE UNITED STATES

FOR VALUE RECEIVED, I, **Makoto Higashikawa**

hereby sell, assign, transfer and convey unto **CANON KABUSHIKI KAISHA**

a corporation of **Japan**

having a place of business at

3-30-2, Shimomaruko, Ohta-ku, Tokyo, Japan

its successors, assigns and legal representatives (hereinafter called the "Assignee"), the entire right, title and interest, for the United States, in and to certain inventions relating to

METHOD OF FORMING SEMICONDUCTOR DEVICE

and described in an application for Letters Patent of the United States filed by me on **April 30, 2004** and which has been accorded Application No. **10/834,836**

and in and to said application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted, thereon, and all reissues and extensions thereof; and I hereby authorize and request the Commissioner for Patents and Trademarks of the United States to issue all Letters Patent upon said inventions to the Assignee or to such nominees as it may designate.

AND I authorize and empower the said Assignee or nominees to invoke and claim for any application for patent or other form of protection for said inventions, the benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from me.

AND I hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any assignment, consent to file or like document which may be required in the United States for any purpose and more particularly in proof of the right of said Assignee or nominees to claim the aforesaid benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it.

AND I hereby covenant that I have the full right to convey the entire right, title and interest herein assigned and that I have not executed and will not execute any agreement in conflict herewith.

AND I hereby covenant and agree that I will communicate to said Assignee or nominees all facts known to me pertaining to said inventions, and testify in all legal proceedings, sign all lawful papers, execute all continuing and reissue applications, make all rightful oaths and declarations and in general perform all lawful acts necessary or proper to aid said Assignee or nominees in obtaining, maintaining and enforcing all lawful patent protection for said inventions in the United States.

By: Makoto Higashikawa
Makoto Higashikawa

Date: June 2 2004